

(12) **United States Design Patent**
Chen

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(54) **SEMI-ROUND SENSOR CAN**

(71) Applicant: **EKO DEVELOPMENT LTD.,**
Guangzhou (CN)

(72) Inventor: **Yizhi Chen,** Guangzhou (CN)

(73) Assignee: **EKO Development Ltd.,** Guangzhou (CN)

(**) Term: **15 Years**

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(51) **LOC (14) Cl.** **09-09**

(52) **U.S. Cl.**
USPC **D34/9**

(58) **Field of Classification Search**
USPC D34/7, 8, 9
CPC B65F 1/006; B65F 1/1638; B65F 2001/1653; B65F 2001/1661; B65F 2001/1669; B65F 2001/1676; B65F 2001/1684; B65F 2001/1692; B65F 1/1426

See application file for complete search history.

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Primary Examiner — Antoine Duval Davis

(74) Attorney, Agent, or Firm — William H. Dippert; Laurence A. Greenberg; Werner H. Stemer

(57) **CLAIM**

The ornamental design for a semi-round sensor can, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semi-round sensor can, showing my new design.

FIG. 2 is a top plan view thereof.

FIG. 3 is a front elevation view thereof.

FIG. 4 is a right-side elevation view thereof.

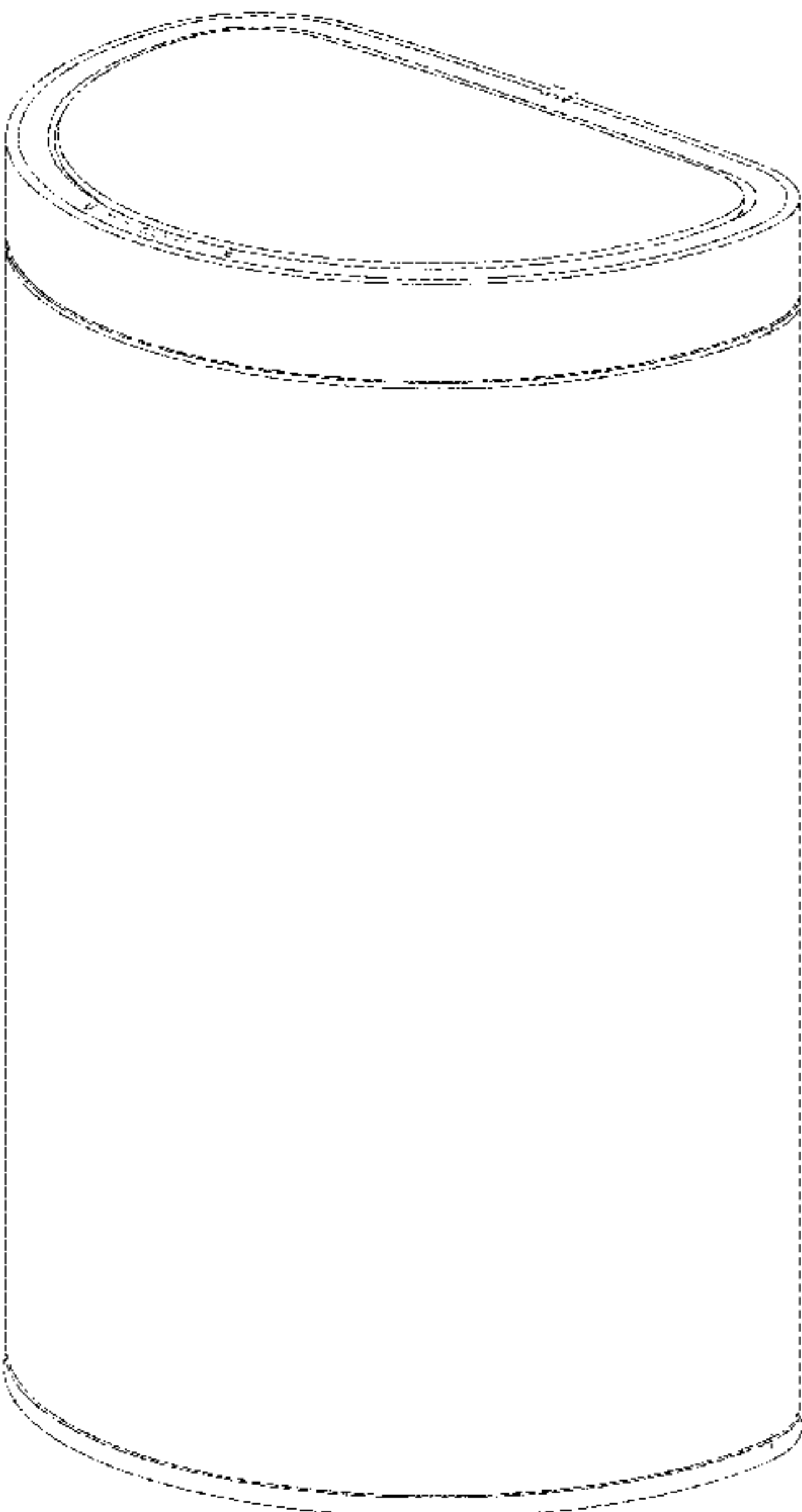
FIG. 5 is a rear elevation view thereof.

FIG. 6 is a bottom plan view thereof; and,

FIG. 7 is a left-side elevation view thereof.

The broken lines in the drawings depict portions of the semi-round sensor can that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



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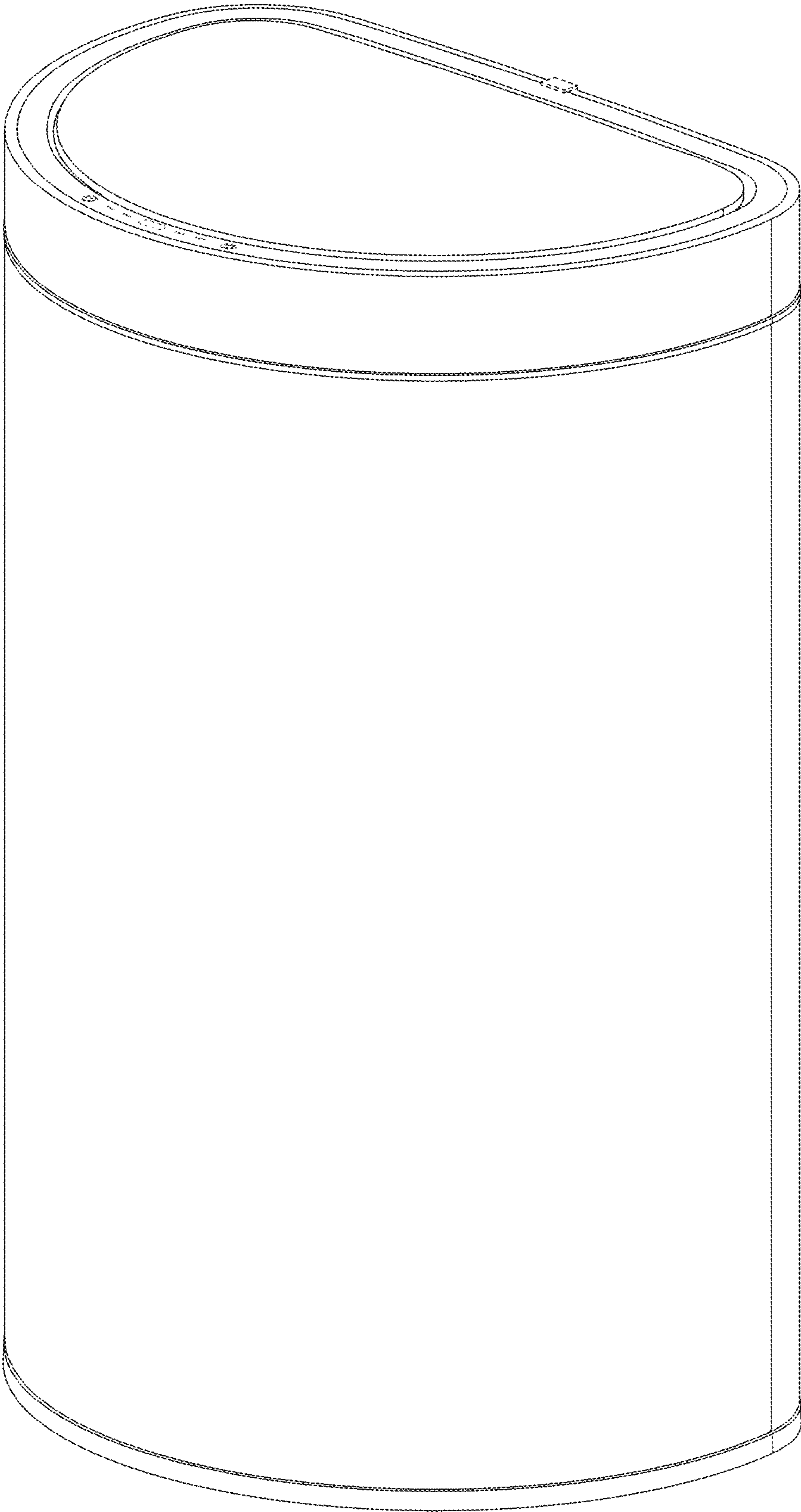


FIG. 1

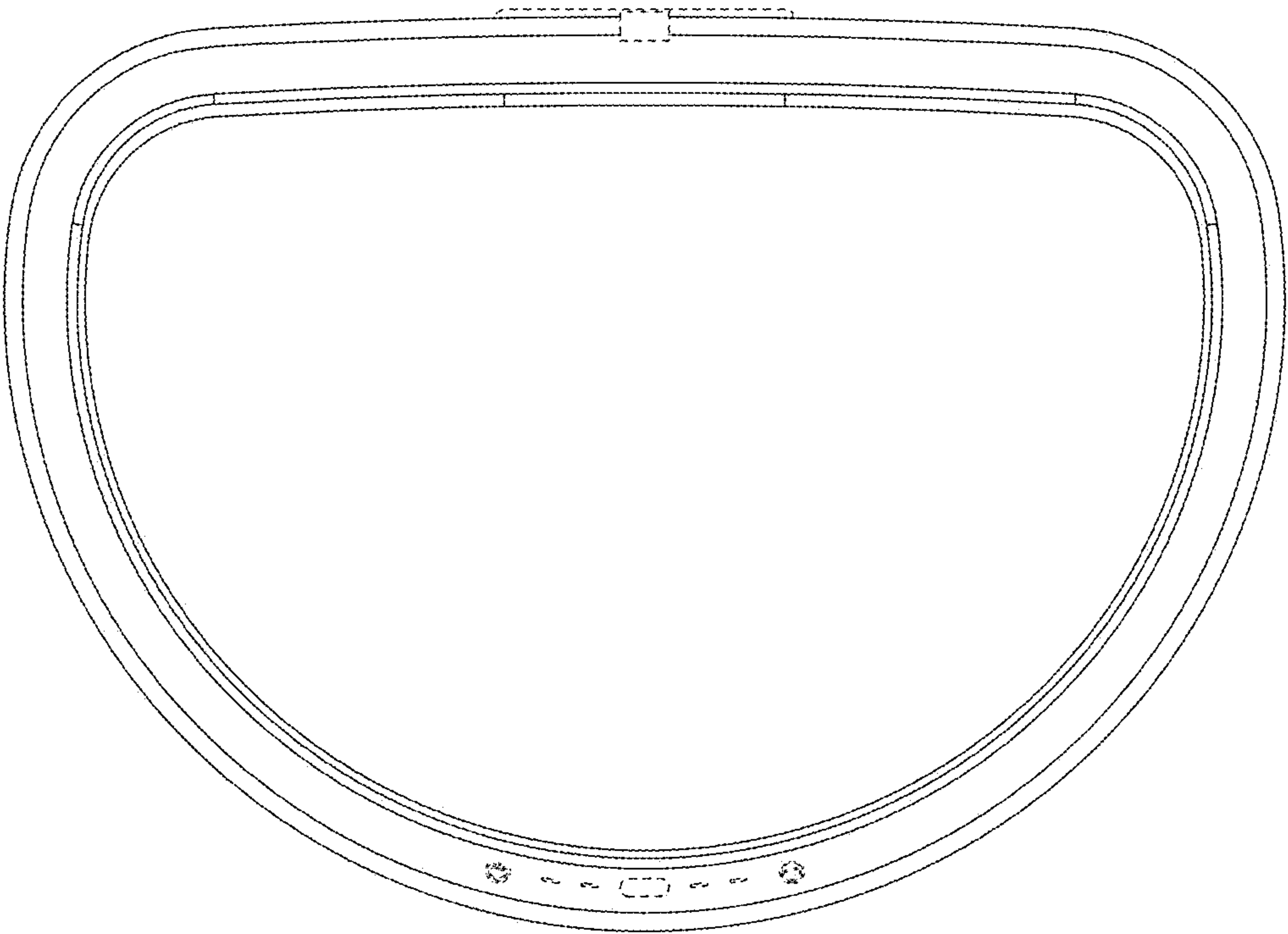


FIG. 2

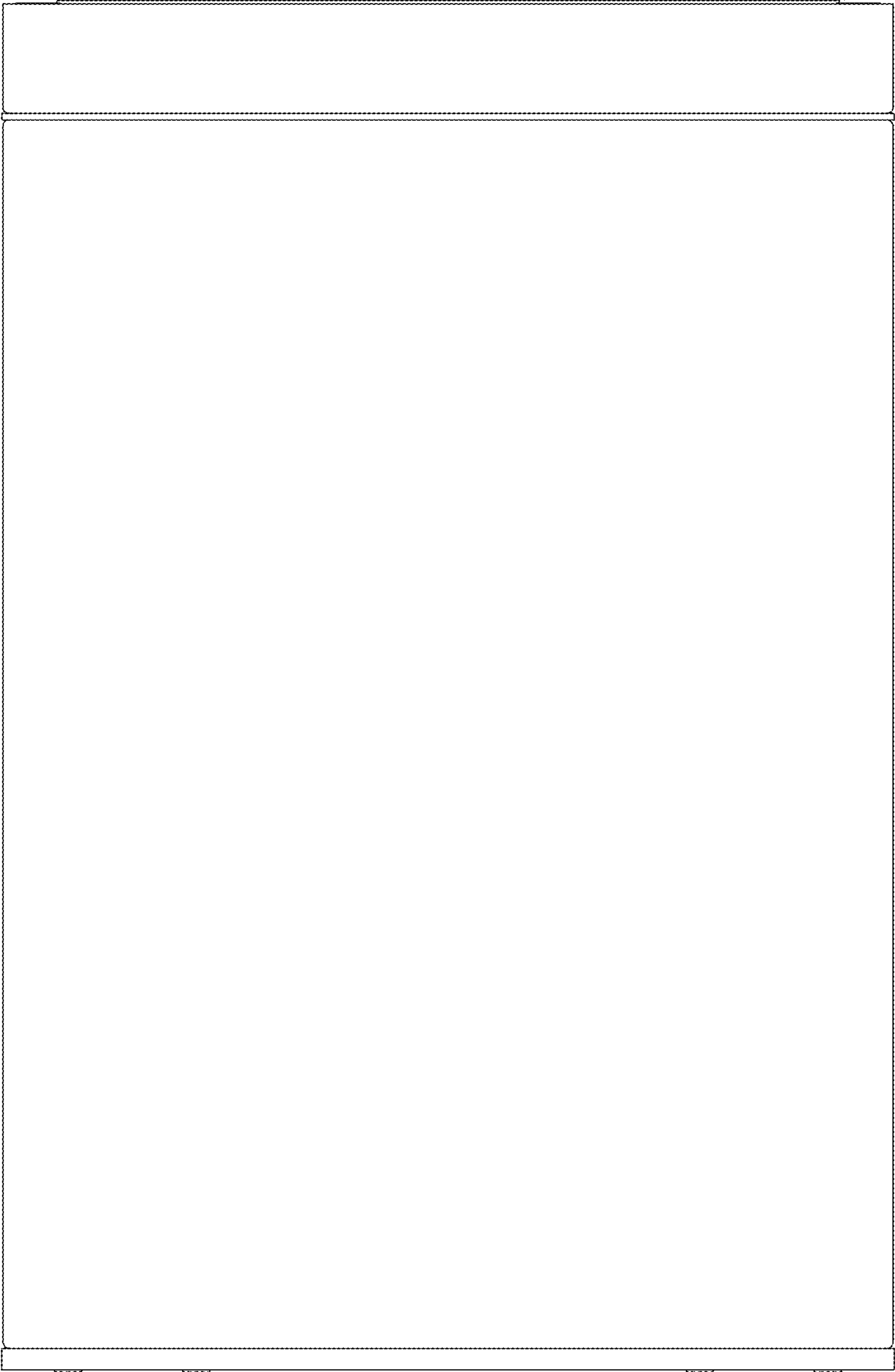


FIG. 3

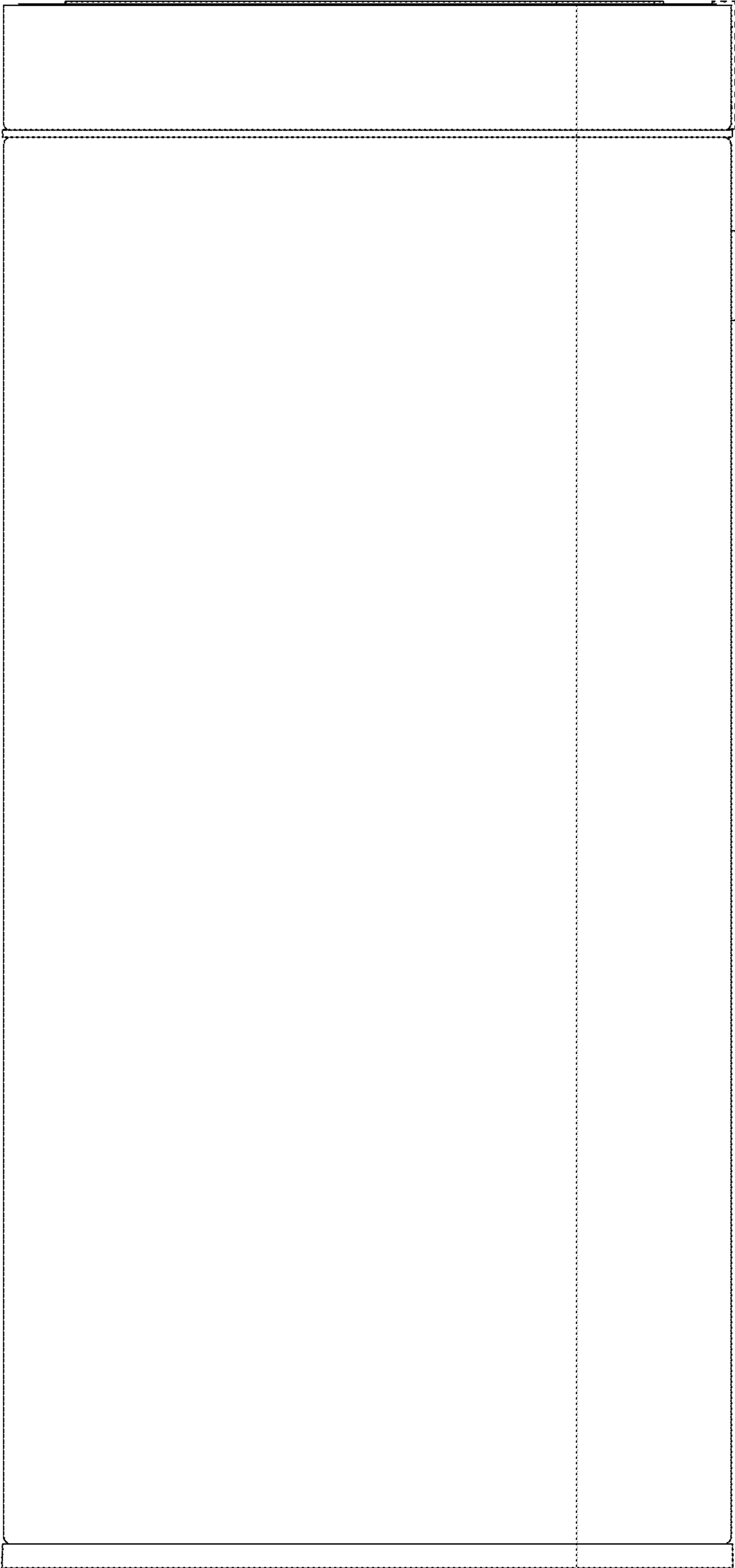


FIG. 4

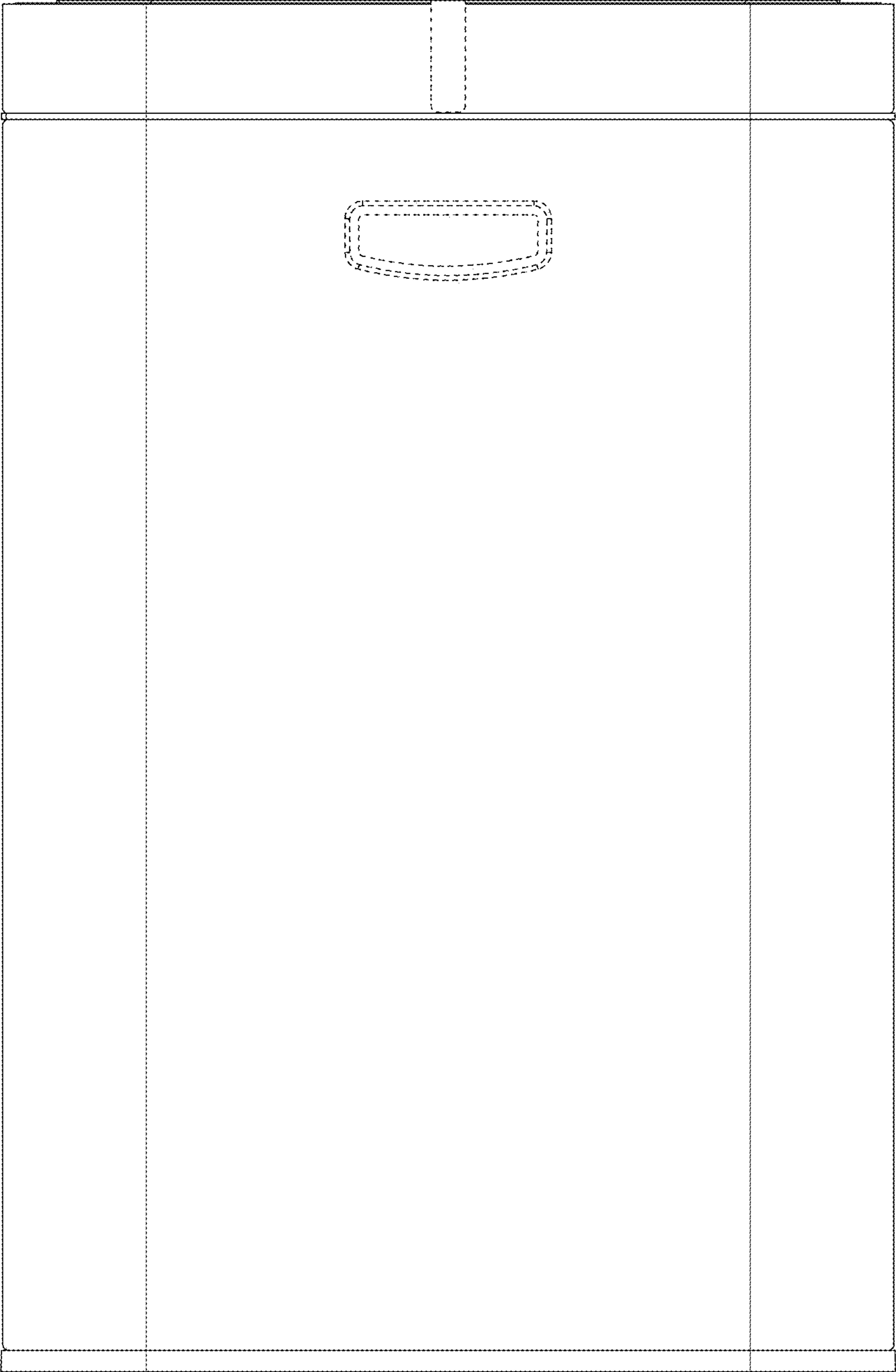


FIG. 5

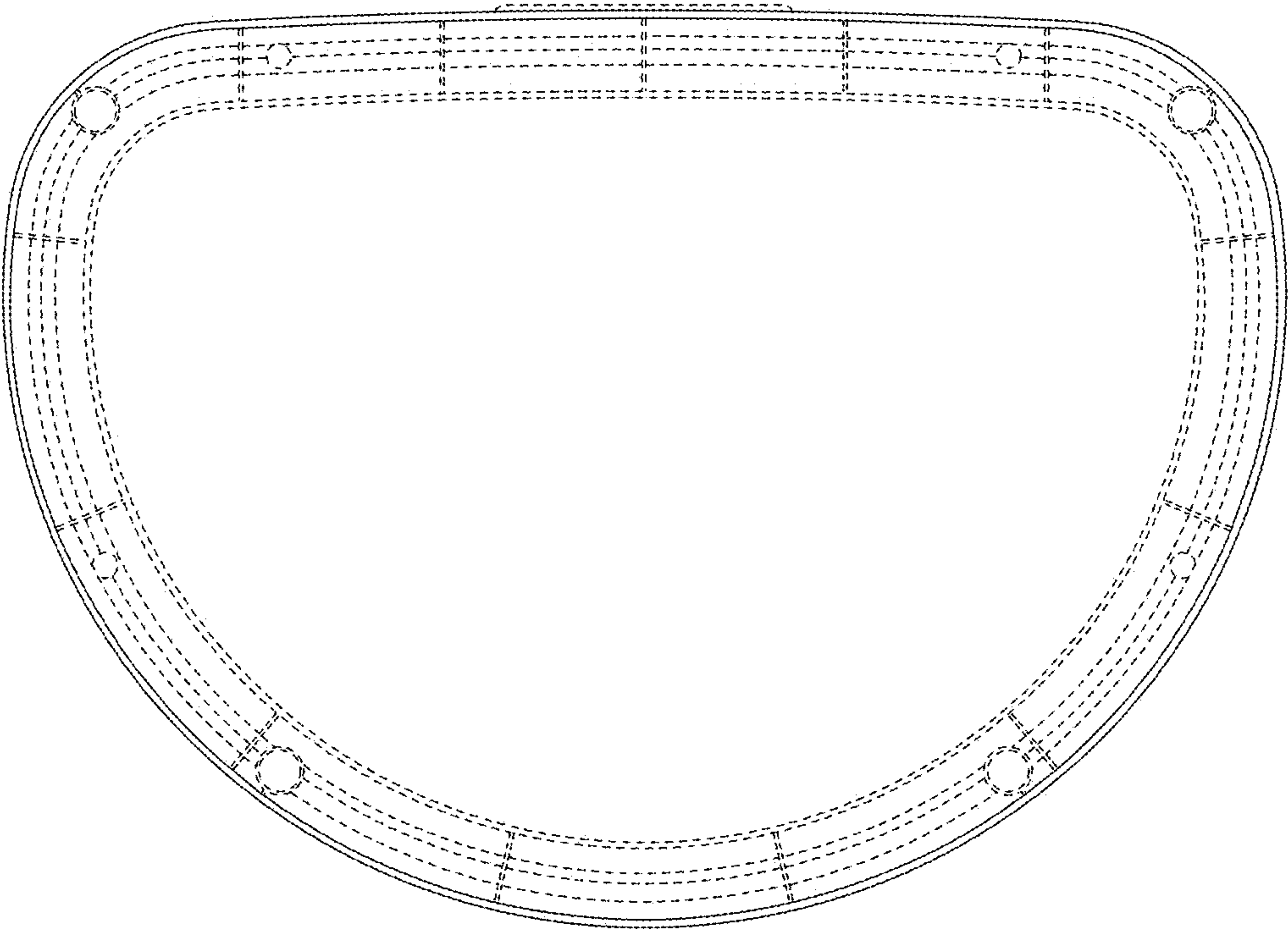


FIG. 6

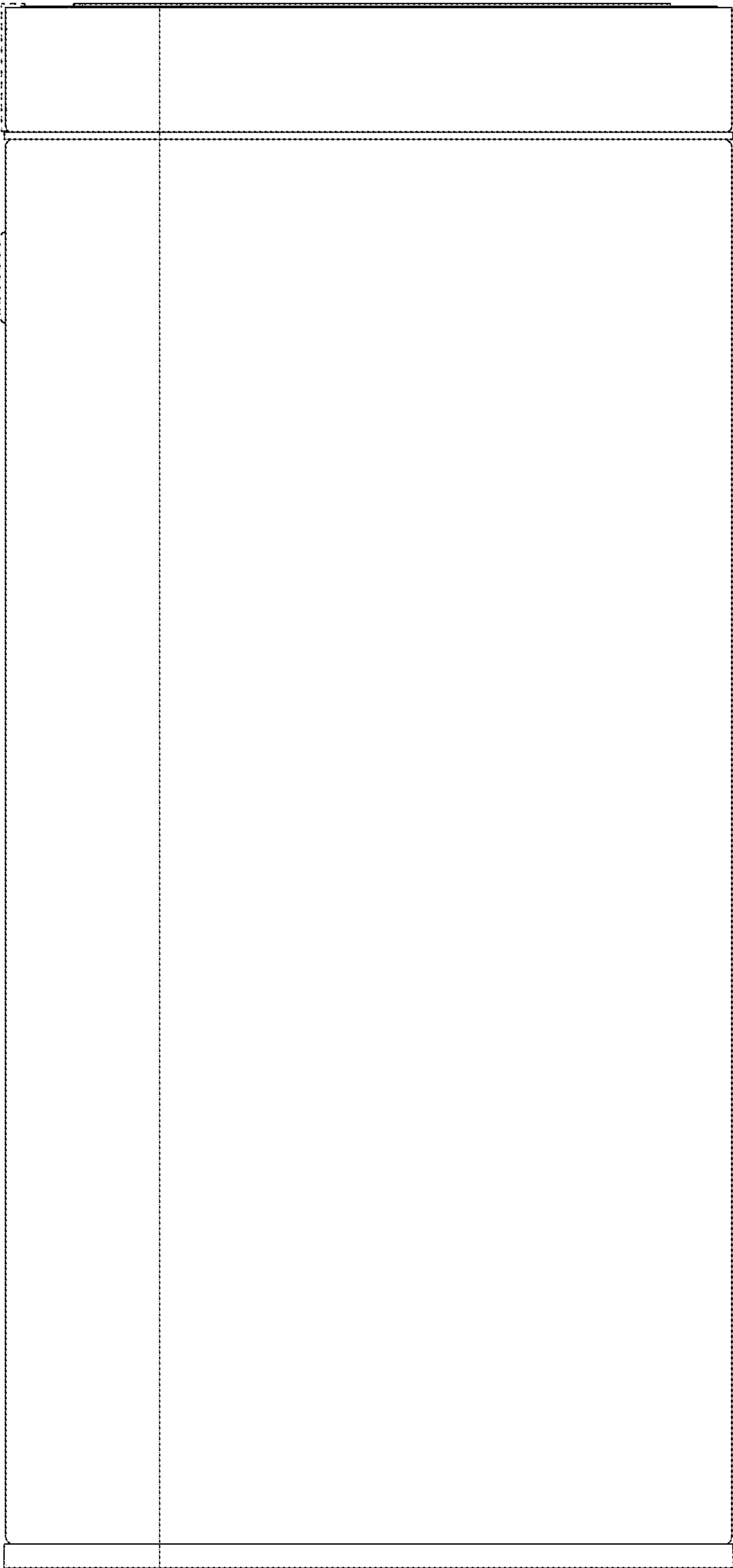


FIG. 7